The SWAM-BLASTER® line of Micro Abrasive
Blasters are complete, accurate and precise.

With independently adjustable powder flow control and air pressure regulation, Total Process Control can be achieved.

The SWAM BLASTERs introduce a defined amount of abrasive powder into a controlled stream of compressed air through the abrasive pathway and out of a selected nozzle tip. When detail is required, the powder flow can be turned down to reduce the amount of powder being introduced into the abrasive pathway thus, allowing the use of a very small nozzle tip. For more aggressive requirements, the air pressure, powder flow and the nozzle tip diameter can be increased.

The basic design of the Model EV-2 Micro Abrasive Blaster and the



Model EV-2L is an "Economical Version" for the moderate applications with brass fittings throughout the abrasive pathway. The Model EV-2 has a nozzle range from .007" up to .040" and for more aggressive applications that require a larger nozzle range, the Model EV-2L is suitable from .018" up to .060".

The unique design of the Model MV-2 Micro Abrasive Blaster and the



Model MV-2L offers "Maximum Versatility" with carbide lined fittings throughout the abrasive pathway and with the tilting powder tank that is mounted to a hinged plate to allow it to tilt to the side and with the push of a button, the vibrator activates to simply walk the powder out for rapid powder changes.

The optimum nozzle range for the Model MV-2 is from .007" up to .040" and the Model MV-2L is from .018" up to .060" for the more aggressive applications.

Abrasive Powders/ Hardness	CMI#	Abrasive Size
Silicon Carbide Knoop 2500, Mohs 9.0+	#38	60 micron
Aluminum Oxide Knoop 2000, Mohs 9.0	#50	12 micron
	#14	17.5 micron
	#16	27.5 micron
	#17	27 micron
Aluminum Oxide (white) Knoop 2000, Mohs 9.0	#33	50 micron
Crushed Glass Mohs 5.5	#40	64 micron
Glass Beads Mohs 5.5	#39	44 micron
Dolomite Mohs 3.5	#30	44 micron
Plastic Blast Mohs 3.5	#45	160 micron
Soda Bicarbonate Mohs 2.5	#34	75 micron
Carbo Blast 80+/-10 shore, D scale	#25	110 micron
	#25A	160 micron

The Model MV-241 Micro Abrasive Blaster is the ultimate in "Maximum"



Versatility". This model is a combination of the precise ability of the Model MV-2 and the aggressive attitude of the Model MV-2L in one unit. Just press the toggle switch on the front panel to green to use nozzles from .011" up to .032" or press the switch to amber to use nozzles from .018" up to .060".

The Model LV-1 (Large Volume) Micro Abrasive Blaster is best for operating in production lines and in the SWAM® Automated Systems. The Model LV-1 features an hour meter for SPC monitoring and a leak detection system for the pinch valve assemblies. It holds approximately 20 pounds of aluminum oxide and has a separate mixing powder tank for a consistent

powder feed rate from a full tank to an empty tank.



For applications where the Model LV-1 is not quite enough, the Model XV-1 (Xstream™ Volume)

Micro Abrasive Blaster is the solution for the heaviest output requirements. Similar to the LV-1, it is equipped with larger hoses and fittings throughout the abrasive/air pathway.

The Model LV-1 works very well with a nozzle range from .018" up to .060". For the Model XV-1, the optimum nozzle range is .032" up to .090".

Accessories

Work Chambers, small, standard, big or custom









Dust Collectors

1 hp to 20 hp



All in One Work Chamber & Dust Collection



TURBO-Max Bench Top System



Work Cell, on wheels put it where needed

We Automate Systems

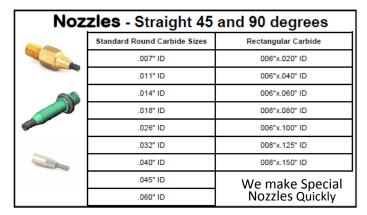




Wafer Coring

SCR Beveler

Belt Abrader





Consider the Possibilities of Micro Abrasive Blasting

Micro abrasive blasting has a wide variety of applications within many industries including Semiconductor, Electronics, Machine Shops, Museums, Medical, Dental Labs, as well as Arts and Crafts.



Artifact Preparation Art Restoration Artwork

Ceramics Cleaning

Coating Removal

Component Demarking

Conformal Coating Removal

Cutting

De-burring

De-capsulation

De-flashing

Delicate Stain Removal

Dental Lab Drilling

EDM Recast Removal

Engraving

Epoxy Removal

Etching

Failure Analysis

Fossil and Mineral Matrix Removal

Gemstone Preparation

Glass Engraving and Etching

Glass to Metal Seal Work

Gold Removal

Gold Surface Preparation

ID Marking

Insulation Removal

Investment Plaster Removal

Jewelry Cleaning

Jewelry Preparation

Laser Slag Removal



Lead Frame De-flashing Magnetic Head Work Micro Hole Drilling Mirror Backing Removal

Mold Polishing & Texturing

Oxidation Removal

Part Marking

PCB Rework & Repair

Piezo Fabrication

Plating Removal

Polishing

Porcelain Crown Preparation

Pottery Cleaning

Power Device Beveling

Probe Card Cleaning

Solder Mask Removal

Surface Finishing

Surface Preparation

Surface Texturing

Thermocouple Processing

Thin Wall Tube Drilling

Trimming of:

Resistors

Capacitors

Thermistors

Wafer Edge Rounding and Contouring

Wafer Cutting

Wafer Fabrication

Wafer Gettering

Wafer Slot Hole Drilling

And Much More **Consider the Possibilities**

613 Justin Avenue Glendale, California 91201-2396 (818)240-7520 • (800)659-7926 • FAX (818)247-3574 www.crystalmarkinc.com • sales@crystalmarkinc.com

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